



# Specification for Approval

Date: 2020/9/11





Customer: 深圳臺慶

	TAI-TECH P/N:	HCB3216KV-310T3	80							
,	CUSTOMER P/N:									
,	DESCRIPTION:									
	QUANTITY:	pcs	<u> </u>							
REMARK:										
	Cu	stomer Approval Feedba	ick							

#### 西北臺慶科技股份有限公司 TAI-TECH Advanced Electronics Co., Ltd

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# High Current Ferrite Chip Bead(Lead Free)

HCB3216KV-310T30

ECN HISTORY LIST									
REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWN				
1.0	14/01/24	變更電鍍錫層厚度 3.0um min.=>3.5um min.	楊祥忠	羅培君	張嘉玲				
2.0	14/08/01	變更 Reflow 圖示	楊祥忠	羅培君	張嘉玲				
2.1	14/08/01	修正包裝帶尺寸	楊祥忠	羅培君	張嘉玲				
3.0	16/01/26	修訂下列可靠度溫度同 Operating Temperature 1.High Temperature Exposure(Storage) 2.High Temperature Operational Life 3.Thermal shock 4.Temperature Cycling	楊祥忠	詹偉特	張嘉玲				
4.0	17/02/16	修訂 Recommended PC Board Pattern	楊祥忠	詹偉特	張嘉玲				
5.0	20/08/01	更新 Reflow 依 IPC EDEC J-STD-020E	鄧福興	浦冬生	王俞琴				
備		ı	I						
註									

TAI-TECH KBM01-200900263 P2.

# High Current Ferrite Chip Bead(Lead Free)

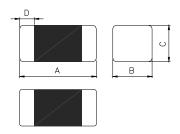
HCB3216KV-310T30

Certificate

### 1.Features

- 1. Monolithic inorganic material construction.
- 2. Closed magnetic circuit avoids crosstalk.
- 3. Suitable for reflow soldering.
- 4. Shapes and dimensions follow E.I.A. spec.
- 5. Available in various sizes.
- 6. Excellent solder ability and heat resistance.
- 7. High reliability. Reliability test meet AEC-Q200.
- 8. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
- 9. Low DC resistance structure of electrode to prevent wasteful electric power consumption.
- 10. Operating Temperature: -55~+150°C (Including self-temperature rise)

### 2.Dimensions



Chip Size				
Α	3.20±0.20			
В	1.60±0.20			
С	1.10±0.20			
D	0.50±0.30			

Units: mm

### 3.Part Numbering



V=Vehicle

310=31 $\Omega$ 

C: Material

D: Category Code

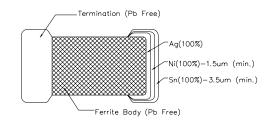
E: Impedance

F: Packaging

G: Rated Current

T=Taping and Reel, B=Bulk(Bags)

30=3000mA

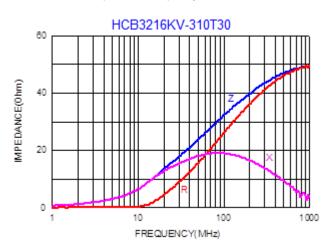


### 4. Specification

Tai-Tech Part Number	Impedance ( $\Omega$ )	Test Frequency (Hz)	DC Resistance $(\Omega)$ max.	Rated Current (mA) max.
HCB3216KV-310T30	31±25%	60mV/100M	0.04	3000

- Rated current: based on temperature rise test
- In compliance with EIA 595

#### Impedance-Frequency Characteristics



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### 5. Reliability and Test Condition

Item		Performance		Test Condition
Series No.	FCB	FCM	HCB	_
Operating Temperature		-55∼+150 $^{\circ}$ C (Including self-temperature r	ise)	-
Transportation Storage Temperature		-55~+150℃ (on board)		For long storage conditions, please see the Application Notice
Impedance (Z)				Agilent4291 Agilent E4991 Agilent4287 Agilent16192
DC Resistance	Refer to standard electi	rical characteristics list		Agilent 4338
Rated Current				DC Power Supply Over Rated Current requirements, there will be some risk
Temperature Rise Test	Rated Current < 1A $\Delta$ T 2 Rated Current $\geq$ 1A $\Delta$ T			Applied the allowed DC current.     Temperature measured by digital surface     Thermometer.
High Temperature Exposure(Storage)				Preconditioning:Run through IR reflow for 3 times.( IPC/JEDEC J-STD-020E Classification Reflow Profiles Temperature: 150±2°C Duration: 1000hrs Min. Measured at room temperature after placing for 24±2 hrs
Temperature Cycling	Appearance: No dama Impedance: within±15 Inductance: within±10 Q: Shall not exceed th RDC: Within ±15% of	% of initial value % of initial value	Preconditioning:Run through IR reflow for 3 times.( IPC/JEDEC J-STD-020E Classification Reflow Profiles Condition for 1 cycle Step1 : -55±2℃ 30min Min Step2 : 150±2℃ transition time 1min MAX. Step3 : 150±2℃30min Min. Step4 : Low temp. transition time 1min MAX. Number of cycles : 1000 Measured at room temperature after placing for 24±2 hrs	
Biased Humidity (AEC-Q200)	Appearance : No dama Impedance : within±15	wof initial value		Preconditioning:Run through IR reflow for 3 times.( IPC/JEDEC J-STD-020E Classification Reflow Profiles Humidity :85±3%RH. Temperature :85±2°C. Duration :1000 hrs Min. Measured at room temperature after placing for 24±2 hrs
High Temperature Operational Life	Inductance: within±10' Q: Shall not exceed th RDC: Within ±15% of	Preconditioning:Run through IR reflow for 3 times.( IPC/JEDEC J-STD-020E Classification Reflow Profiles Temperature: 150±2°C Duration: 1000hrs Min. with 100% rated current. Measured at room temperature after placing for 24±2 hrs		
External Visual	Appearance : No dama	nge.		Inspect device construction, marking and workmanship. Electrical Test not required.
Physical Dimension	According to the product	t specification size measuren		According to the product specification size measurement
Resistance to Solvents	Appearance : No damaç	ge.		Add aqueous wash chemical - OKEM clean or equivalent.

**TAI-TECH** KBM01-200900263 P4.

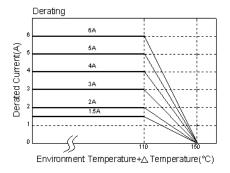
Item	Performance		Te	st Con	dition		
			PC/JED Profiles	EC J-STE	ugh IR refle 0-020E Clas		
Mechanical Shock		Туре	Peak alue (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec	
		SMD	100	6	Half-sine	12.3	
		Lead	100	6	Half-sine	12.3	
		3 shoo			direction a	along 3	
Vibration	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: Within ±15% of initial value and shall not exceed the specification value	Preconditioning:Run through IR reflow for 3 times.( IPC/JEDEC J-STD-020E Classification Reflow Profiles Oscillation Frequency: 10Hz ~ 2KHz ~ 10Hz for 20 minute Equipment: Vibration checker Total Amplitude:5g Testing Time: 12 hours(20 minutes, 12 cycles each of 3 orientations) °					
		Test con Number	,		202 Condition	on B)	
Resistance to Soldering		Tempera (°C		Time (s)	Temperaturamp/immeand emers	ersion	
Heat		260 ±5 (solder t		10 ±1	25mm/s		
		Depth: completely cover the termination					
Thermal shock	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: Within ±15% of initial value and shall not exceed the specification value	Preconditioning:Run through IR reflow fotimes. (IPC/JEDEC J-STD-020E Classifica Reflow Profiles Condition for 1 cycle Step1: -55±2°C 15±1min Step2: 150±2°C within 20 Sec. Step3: 150±2°C 15±1min Number of cycles: 300 Measured at room temperature after place for 24±2hrs				ssification	
ESD	Appearance : No damage.	Time (ns)					
			a.Method B, 4 hrs @155°C dry heat @235°C±5°C Test time:5 +0/-0.5 seconds.				
Solder ability	More than 95% of the terminal electrode should be covered with solder.	b. Method D category 3. (steam aging 8hours $\pm$ 15 min)@ 260°C $\pm$ 5°C Test time: 30 +0/-0.5 seconds.					
Electrical Characterization	Refer Specification for Approval	Summary to show Min, Max, Mean and Standard deviation					
Flammability	Electrical Test not required.	V-0 or \	/-1 are	accepta	ble.		

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Item		Performance	Test Condition
Board Flex	Appearance : No damage.	Support Solder Chip Printed circuit board before testing  45+2  45+2  Radius 340  Printed circuit board under test  Displacement	Preconditioning:Run through IR reflow for 3 times.( IPC/JEDEC J-STD-020E Classification Reflow Profiles Place the 100mm X 40mm board into a fixture similar to the one shown in below Figure with the component facing down. The apparatus shall consist of mechanical means to apply a force which will bend the board (D) x = 2 mm minimum. The duration of the applied forces shall be 60 (+ 5) sec. The force is to be applied only once to the board.
Terminal strength	Appearance : No damage.	substrate priess tool shear force	Preconditioning:Run through IR reflow for 3 times.( IPC/JEDEC J-STD-020E Classification Reflow Profiles With the component mounted on a PCB with the device to be tested, apply a 17.7 N (1.8 Kg) force to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to thecomponent being tested.

### \*\*Derating Curve

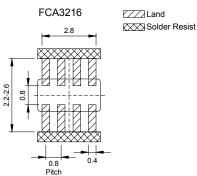
For the ferrite chip bead which withstanding current over 1.5A, as the operating temperature over 110°C, the derating current information is necessary to consider with. For the detail derating of current, please refer to the Derated Current vs. Operating Temperature curve.



### 6. Soldering and Mounting

### 6-1. Recommended PC Board Pattern

Chip Size							Pattern w Sold	
Series	Туре	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	F(mm)	G(mm)
	1005	1.0±0.10	0.50±0.10	0.50±0.10	0.25±0.10	0.50	0.40	0.60
FCB	1606	1.6±0.15	0.80±0.15	0.60±0.15	0.30±0.20	0.80	0.85	0.95
FCM	1608	1.6±0.15	0.80±0.15	0.80±0.15	0.30±0.20	0.80	0.85	0.95
HCB	0040	2.0±0.20	1.25±0.20	0.85±0.20	0.50±0.30	4.05	1.00	1.45
GHB	2012	2.0±0.20	1.25±0.20	1.25±0.20	0.50±0.30	1.05		
FCI	<mark>3216</mark>	3.2±0.20	1.60±0.20	1.10±0.20	0.50±0.30	<mark>1.05</mark>	<mark>2.20</mark>	1.80
FHI	3225	3.2±0.20	2.50±0.20	1.30±0.20	0.50±0.30	1.05	2.20	2.70
FCH	4516	4.5±0.20	1.60±0.20	1.60±0.20	0.50±0.30	1.05	3.30	1.80
HCI	4532	4.5±0.20	3.20±0.20	1.50±0.20	0.50±0.30	1.05	3.30	3.40





PC board should be designed so that products can prevent damage from mechanical stress when warping the board.

#### 6-2. Soldering

Mildly activated rosin fluxes are preferred. TAI-TECH terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

#### 6-2.1 IR Soldering Reflow:

Recommended temperature profiles for lead free re-flow soldering in Figure 1. Table 1.1&1.2 (J-STD-020E)

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### 6-2.2 Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended. (Figure 2.)

- Preheat circuit and products to 150°C
  350°C tip temperature (max)
- · Never contact the ceramic with the iron tip

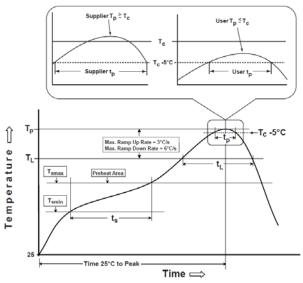
• 1.0mm tip diameter (max)

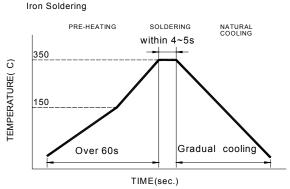
• Use a 20 watt soldering iron with tip diameter of 1.0mm

Fig.2 Iron soldering temperature profiles

· Limit soldering time to 4~5sec.

Fig.1 IR Soldering Reflow





Iron Soldering times: 1 times max

Reflow times: 3 times max

Table (1.1): Reflow Profiles

Profile Type:	Pb-Free Assembly
$eq:total_continuous_cont$	150℃ 200℃ 60-120seconds
Ramp-up rate( $T_L$ to $T_p$ )	3°C/second max.
	217℃ 60-150 seconds
Classification temperature(T <sub>c</sub> )	See Table (1.2)
Time(tp) at Tc- $5^{\circ}\mathrm{C}$ (Tp should be equal to or less than Tc.)	< 30 seconds
Ramp-down rate(T <sub>p</sub> to T <sub>L</sub> )	6°C /second max.
Time 25℃ to peak temperature	8 minutes max.

Tp: maximum peak package body temperature, Tc: the classification temperature.

For user (customer) **Tp** should be equal to or less than **Tc**.

Table (1.2) Package Thickness/Volume and Classification Temperature (Tc)

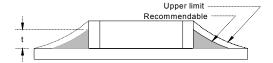
	Package	Volume mm <sup>3</sup>	Volume mm <sup>3</sup>	Volume mm <sup>3</sup>
	Thickness	<350	350-2000	>2000
	<1.6mm	260°C	260°C	260°C
PB-Free Assembly	1.6-2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

Reflow is referred to standard IPC/JEDEC J-STD-020E •

#### 6-2.3 Solder Volume:

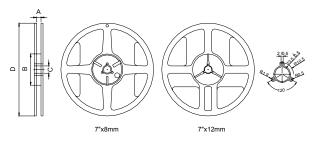
Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance. Solder shall be used not to be exceed as shown in right side:

Minimum fillet height = soldering thickness + 25% product height



### 7. Packaging Information

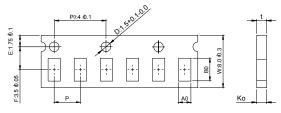
### 7-1. Reel Dimension



Туре		A(mm)	B(mm)	C(mm)	D(mm)	
	<mark>7"x8mm</mark>	9.0±0.5	<mark>60±2</mark>	<mark>13.5±0.5</mark>	<mark>178±2</mark>	
7"x12mm		13.5±0.5	60±2	13.5±0.5	178±2	

#### 7-2.1 Tape Dimension / 8mm

### ■Material of taping is paper

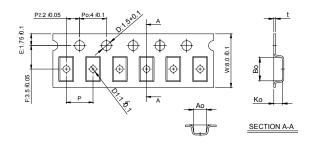


P2:2:0.1	P0:4	0.1 2) 180 A	-	t
F:3.5 Ø.1	P		k Ko	

Ī	Size Bo(mm)		Ao(mm)	Ko(mm)	P(mm)	t(mm)	
	100505	1.12±0.03	0.62±0.03	0.60±0.03	2.0±0.05	0.60±0.03	

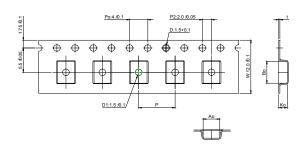
Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
160806	1.78±0.03	0.97±0.03	0.75±0.03	4.0±0.10	0.75±0.03
160808	1.80±0.05	0.96+0.05/-0.03	0.95±0.05	4.0±0.10	0.95±0.05
201209	2.10±0.05	1.30±0.05	0.95±0.05	4.0±0.10	0.95±0.05

#### ■Material of taping is plastic



Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)	D1(mm)
201212	2.10±0.10	1.28±0.10	1.28±0.10	4.0±0.10	0.22±0.05	1.0±0.10
<mark>321611</mark>	3.35±0.10	1.75±0.10	1.25±0.10	4.0±0.10	0.23±0.05	1.0±0.10
322513	3.42±0.10	2.77±0.10	1.55±0.10	4.0±0.10	0.22±0.05	1.0±0.10
321609	3.40±0.10	1.77±0.10	1.04±0.10	4.0±0.10	0.22±0.05	1.0±0.10

### 7-2.2 Tape Dimension / 12mm



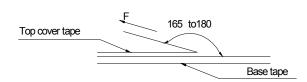
	Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)	D1(mm)
	451616	4.70±0.10	1.75±0.10	1.75±0.10	4.0±0.10	0.24±0.05	1.5±0.10
•	453215	4.70±0.10	3.45±0.10	1.60±0.10	8.0±0.10	0.24±0.05	1.5±0.10

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#### 7-3. Packaging Quantity

Chip Size	453215	451616	322513	<mark>321611</mark>	321609	201212	201209	160808	160806	100505
Chip / Reel	1000	2000	2500	<mark>3000</mark>	3000	2000	4000	4000	4000	10000
Inner box	4000	8000	12500	<mark>15000</mark>	15000	10000	20000	20000	20000	50000
Middle box	20000	40000	62500	<mark>75000</mark>	75000	50000	100000	100000	100000	250000
Carton	40000	80000	125000	<mark>150000</mark>	150000	100000	200000	200000	200000	500000

#### 7-4. Tearing Off Force



The force for tearing off cover tape is 15 to 60 grams in the arrow direction under the following conditions.

Room Temp.	Room Temp. Room Humidity		Tearing Speed
(℃)	(%)	(hPa)	mm/min
5~35	45~85	860~1060	300

### **Application Notice**

Storage Conditions(component level)

To maintain the solderability of terminal electrodes:

- 1. TAI-TECH products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
- 3. Recommended products should be used within 12 months from the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
  - 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
  - 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
  - ${\it 3. } \ {\it Bulk handling should ensure that abrasion and mechanical shock are minimized.}$



# **Test Report**

號碼(No.): CE/2019/C0498 日期(Date): 2019/12/10 頁數(Page): 1 of 14

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件(泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA) (中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P. R., CHINA)

以下測試樣品係由申請廠商所提供及確認 (The following sample(s) was/were submitted and identified by/on behalf of the applicant as):

樣品名稱(Sample Description)

FERRITE CHIP BEAD · FERRITE CHIP INDUCTOR · ARRAY · MCF · MCM · YMV · APM SERIES

樣品型號(Style/Item No.)

FERRITE CHIP BEAD · FERRITE CHIP INDUCTOR · ARRAY · MCF · MCM · YMV · APM SERIES

收件日期(Sample Receiving Date)

2019/12/04

測試期間(Testing Period)

2019/12/04 to 2019/12/10

測試結果(Test Results) : 請參閱下一頁 (Please refer to following pages).

Troy Chang / Manager - Vec Signed for and behalf of SĞS TAIWAN LTD.

Chemical Laboratory - Taipei

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25, Wu Chyuan 7th Road, New Taipei Industrial Park, Wu Ku District, New Taipei City, Taiwan /新士市五股區新北麻業園區五權七路25號 SGS Faiwan Ltd. 台灣接種科技股份有限公司 25, Wu Cityuan rin Hosel, New Yaipes Imuusikai rain, 1997 (2018) 14-886 (02):2299 3939 (74-886 (02):2299 (74-886 (02):2299



**Test Report** 

號碼(No.): CE/2019/C0498 日期(Date): 2019/12/10

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### 測試結果(Test Results)

測試部位(PART NAME)No.1

: 整體混測 (MIXED ALL PARTS)

測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	MDL	結果 (Result) No.1
鎬 / Cadmium (Cd)	mg/kg	参考IEC 62321-5 (2013),以感應耦合電 浆發射光譜儀檢測. / With reference	2	n. d.
鉛 / Lead (Pb)	mg/kg	to IEC 62321-5 (2013) and performed by ICP-0ES.	2	n. d.
汞 / Mercury (Hg)	mg/kg	参考IEC 62321-4:2013+ AMD1:2017,以 感應耦合電漿發射光譜儀檢測. / With reference to IEC 62321-4:2013+ AMD1:2017 and performed by ICP-OES.	2	n. d.
六價络 / Hexavalent Chromium Cr(VI)	mg/kg	参考IEC 62321-7-2 (2017),以UV-VIS檢 測. / With reference to IEC 62321-7- 2 (2017) and performed by UV-VIS.	8	n. d.
多溴聯苯總和 / Sum of PBBs	mg/kg		_	n. d.
一溴聯苯 / Monobromobiphenyl	mg/kg		5	n. d.
二溴聯苯 / Dibromobiphenyl	mg/kg	]	5	n. d.
三溴聯苯 / Tribromobiphenyl	mg/kg		5	n. d.
四溴聯苯 / Tetrabromobiphenyl	mg/kg	参考IEC 62321-6 (2015),以氣相層析/	5	n. d.
五溴聯苯 / Pentabromobiphenyl	mg/kg	質譜儀檢測. / With reference to IEC	5	n. d.
六溴聯苯 / Hexabromobiphenyl	mg/kg	62321-6 (2015) and performed by GC/MS.	5	n. d.
七溴聯苯 / Heptabromobiphenyl	mg/kg	] OO/ MO.	5	n, d,
八溴聯苯 / Octabromobiphenyl	mg/kg	Γ	5	n. d.
九溴聯苯 / Nonabromobiphenyl	mg/kg	]	5	n. d.
十溴聯苯 / Decabromobiphenyl	mg/kg		5	n. d.

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測試項目 (Test Items)	單位 (Unit)	测試方法 (Method)	MDL	結果 (Result) No.1
多溴聯苯醚總和 / Sum of PBDEs	mg/kg		<del>-</del>	n. d.
一溴聯苯醚 / Monobromodiphenyl ether	mg/kg		5	n. d.
二溴聯苯醚 / Dibromodiphenyl ether	mg/kg		5	n. d.
三溴聯苯醚 / Tribromodiphenyl ether	mg/kg	A MIDO 00001 0 (0015)	5	n. d.
四溴聯苯醚 / Tetrabromodiphenyl ether	mg/kg	參考IEC 62321-6 (2015),以氣相層析/	5	n. d.
五溴聯苯醚 / Pentabromodiphenyl ether	mg/kg	質譜儀檢測. / With reference to IEC 62321-6 (2015) and performed by	5	n. d.
六溴聯苯醚 / Hexabromodiphenyl ether	mg/kg	GC/MS.	5	n, d.
七溴聯苯醚 / Heptabromodiphenyl ether	mg/kg	007 mg,	5	n. d.
八溴聯苯醚 / Octabromodiphenyl ether	mg/kg		5	n. d.
九溴聯苯醚 / Nonabromodiphenyl ether	mg/kg		5	n. d.
十溴聯苯醚 / Decabromodiphenyl ether	mg/kg		5	n. d.
六溴環十二烷及所有主要被辨別出的異構物 / Hexabromocyclododecane (HBCDD) and all major diastereoisomers identified ( $\alpha$ - HBCDD, $\beta$ - HBCDD, $\gamma$ - HBCDD) (CAS No.: 25637-99-4 and 3194-55-6 (134237-51-7, 134237-50-6, 134237-52-8))	mg/kg	參考IEC 62321 (2008),以氣相層析/質 譜儀檢測. / With reference to IEC 62321 (2008). Analysis was performed by GC/MS.	5	n. d.
鹵素 / Halogen				
鹵素(氟)/ Halogen-Fluorine (F) (CAS No.: 14762-94-8)	mg/kg		50	n. d.
鹵素 (氣) / Halogen-Chlorine (C1) (CAS No.: 22537-15-1)	mg/kg	参考BS EN 14582 (2016),以離子層析儀 分析. / With reference to BS EN	50	n. d.
鹵素(溴)/ Halogen-Bromine (Br) (CAS No.: 10097-32-2)	mg/kg	14582 (2016). Analysis was performed by IC.	50	n. d.
鹵素(碘)/ Halogen-Iodine(I)(CAS No.: 14362-44-8)	mg/kg		50	n. d.

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測試項目 (Test Items)	單位 (Unit)	测試方法 (Method)	MDL	結果 (Result) No.1
鄰苯二甲酸丁苯甲酯 / BBP (Butyl Benzyl phthalate) (CAS No.: 85-68-7)	mg/kg		50	n. d.
鄰苯二甲酸二丁酯 / DBP (Dibutyl phthalate) (CAS No.: 84-74-2)	mg/kg		50	n. d.
鄰苯二甲酸二 (2-乙基己基)酯 / DEHP (Di- (2-ethylhexyl) phthalate) (CAS No.: 117-81-7)	mg/kg		50	n. d.
鄉苯二甲酸二異丁酯 / DIBP (Di-isobutyl phthalate) (CAS No.: 84-69-5)	mg/kg		50	n. d.
癣苯二甲酸二異癸酯 / DIDP (Di- isodecyl phthalate) (CAS No.: 26761- 40-0; 68515-49-1)	mg/kg	參考IEC 62321-8 (2017),以氣相層析/ 質譜儀檢測. / With reference to IEC 62321-8 (2017). Analysis was	50	n. d.
鄰苯二甲酸二異壬酯 / DINP (Di- isononyl phthalate) (CAS No.: 28553- 12-0; 68515-48-0)	mg/kg	performed by GC/MS.	50	n. d.
鄰苯二甲酸二正辛酯 / DNOP (Di-n-octyl phthalate) (CAS No.: 117-84-0)	mg/kg		50	n. d.
鄰苯二甲酸二正己酯 / DNHP (Di-n-hexyl phthalate) (CAS No.: 84-75-3)	mg/kg		50	n. d.
鄉苯二甲酸二戊酯 / DNPP (Di-n-pentyl phthalate) (CAS No.: 131-18-0)	mg/kg		50	n. d.
全氟辛烷磺酸 / Perfluorooctane sulfonates (PFOS-Acid, Metal Salt, Amide)	mg/kg	参考US EPA 3550C (2007),以液相層析/ 質譜儀檢測. / With reference to US EPA 3550C (2007). Analysis was	10	n. d.
全氟辛酸 / PFOA (CAS No.: 335-67-1)	mg/kg	performed by LC/MS.	10	n. d.

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測試項目 (Test Items)	單位 (Unit)	测試方法 (Method)	MDL	結果 (Result) No.1
绨 / Antimony (Sb)	mg/kg	参考US EPA 3052 (1996),以感應耦合電	2	n. d.
鈹 / Beryllium (Be)	mg/kg	漿發射光譜儀檢測. / With reference   to US EPA 3052 (1996). Analysis was	2	n. d.
神 / Arsenic (As)	mg/kg	performed by ICP-OES.	2	n. d.
聚氯乙烯 / Polyvinyl chloride (PVC)	**	以紅外光譜分析及焰色法檢測. / Analysis was performed by FTIR and FLAME Test.	<del>-</del>	Negative

#### 備註(Note):

- 1. mg/kg = ppm : 0.1wt% = 1000ppm
- 2. MDL = Method Detection Limit (方法偵測極限值)
- 3. n.d. = Not Detected (未檢出)
- 4. "-" = Not Regulated (無規格值)
- 5. \*\*= Qualitative analysis (No Unit) 定性分析(無單位)
- 6. Negative = Undetectable 陰性(未偵測到); Positive = Detectable 陽性(已偵測到)
- 7. 樣品的測試是基於申請人要求混合測試,報告中的混合測試結果不代表其中個別單一材質的含量。(The samples was/were analyzed on behalf of the applicant as mixing sample in one testing. The above results was/were only given as the informality value.)

### PFOS參考資訊(Reference Information): 持久性有機污染物 POPs - (EU) 2019/1021

PFOS濃度在物質或製備中不得超過0,001%(10ppm),在半成品、成品或零部件中不得超過0.1%(1000ppm),在紡織品或 塗層材料中不得超過lμg/m²。

(Outlawing PFOS as substances or preparations in concentrations above 0.001% (10ppm), in semi-finished products or articles or parts at a level above 0.1%(1000ppm), in textiles or other coated materials above lug/m<sup>2</sup>.)

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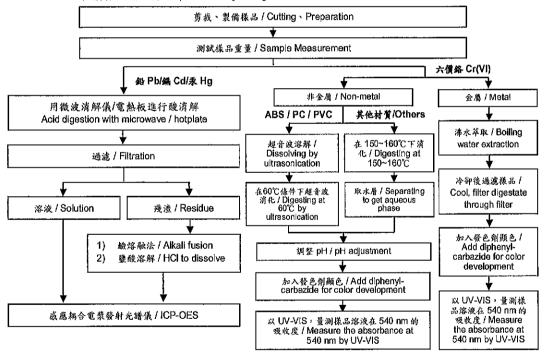
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#### 重金屬流程圈 / Analytical flow chart of Heavy Metal

根據以下的流程圖之條件,樣品已完全溶解。(六價鉻測試方法除外)

These samples were dissolved totally by pre-conditioning method according to below flow chart. (Cr8+ test method excluded)

- 測試人員: 陳恩臻 / Technician ; Rita Chen
- 測試負責人:張啟興 / Supervisor: Troy Chang



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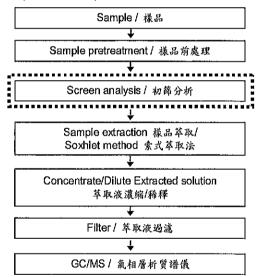
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#### 多溴聯苯/多溴聯苯醚分析流程圖 / Analytical flow chart - PBB/PBDE

- 测试人員:涂雅苓 / Technician: Yaling Tu
- 測試負責人:張啟興 / Supervisor: Troy Chang

初央测试程序 / First testing process -確認程序 / Confirmation process - - - →



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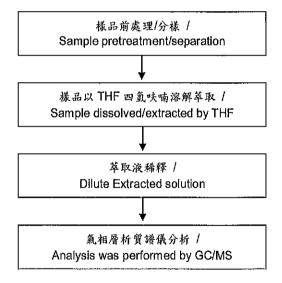
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#### 可塑劑分析流程圖 / Analytical flow chart - Phthalate

測試人員:涂雅苓 / Technician: Yaling Tu

測試負責人:張啟興 / Supervisor: Troy Chang

【测試方法/Test method: IEC 62321-8】



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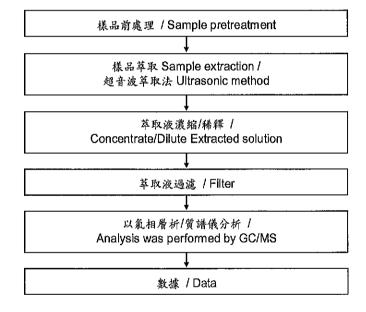
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#### 六溴環十二烷分析流程圖 / Analytical flow chart - HBCDD

- 測試人員:涂雅苓 / Technician: Yaling Tu
- 測試負責人:張啟與 / Supervisor: Troy Chang



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# **Test Report**

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西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件(泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

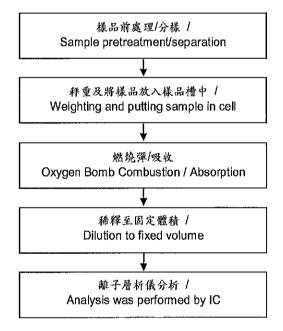
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#### 鹵素分析流程圖 / Analytical flow chart - Halogen

測試人員: 陳恩臻 / Technician: Rita Chen

測試負責人:張啟與 / Supervisor: Troy Chang



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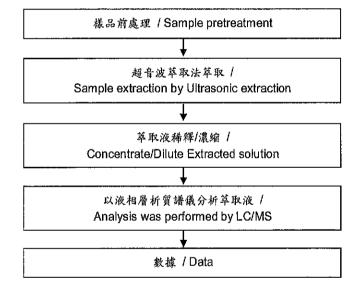
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#### 全氟辛酸/全氟辛烷磺酸分析流程圖 / Analytical flow chart - PFOA/PFOS

- 測試人員:涂雅苓 / Technician: Yaling Tu
- 測試負責人:張啟興 / Supervisor: Troy Chang



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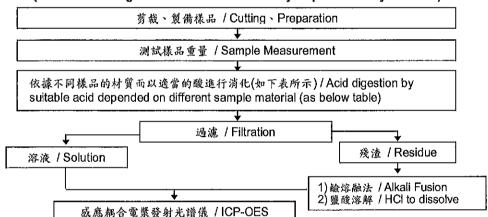
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> 根據以下的流程圖之條件,樣品已完全溶解。 / These samples were dissolved totally by pre-conditioning method according to below flow chart.

- 測試人員:陳恩臻 / Technician: Rita Chen
- 測試負責人:張啟興 / Supervisor: Troy Chang

### 元素以 ICP-OES 分析的消化流程圈 (Flow Chart of digestion for the elements analysis performed by ICP-OES)



鲄,銄,鉊,焊錫 / Steel, copper, aluminum, solder	王水,硝酸,鹽酸,氫氟酸,雙氧水 / Aqua regia, HNO3, HCI, HF, H <sub>2</sub> O <sub>2</sub>
玻璃 / Glass	硝酸,氫氟酸 / HNO3/HF
金,鉑,鈀,陶瓷 / Gold, platinum, palladium, ceramic	王水 / Aqua regia
銀 / Silver	硝酸 / HNO <sub>3</sub>
塑膠 / Plastic	硫酸,雙氧水,硝酸,鹽酸 / H2SO4, H2O2, HNO3, HCI
其他 / Others	加入適當的試劑至完全溶解 / Added appropriate reagent to total digestion

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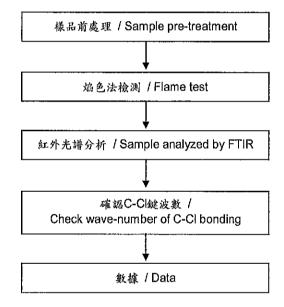
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#### 聚氯乙烯物質判定分析流程圖 / Analysis flow chart - PVC

- 测試人員:涂雅苓 / Technician: Yaling Tu
- 測試負責人:張啟興 / Supervisor: Troy Chang



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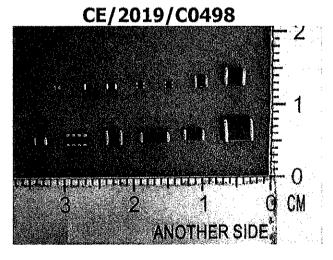
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### \* 照片中如有箭頭標示,則表示為實際檢測之樣品/部位. \*

(The tested sample / part is marked by an arrow if it's shown on the photo.)

CE/2019/C0498 CM



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